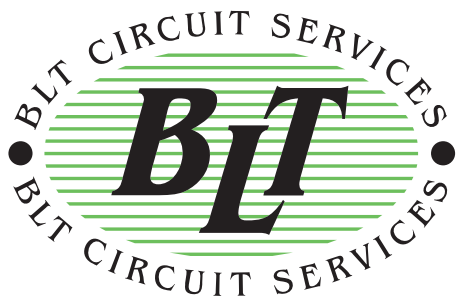


- Kolon Dry Film Resists
- Copper Cleaners and Micro Etch
- Direct Metallisation and Electroplating
- Copper and Tin Plating
- Resist Strippers, Developers and Antifoams
- Desmear and Multilayer Bonding
- Tin Strippers
- HAL Fluxes and Solder
- Solderable Finishes
- Screen Printing Inks and Ancillary Products
- Tapes and Filters
- Water Treatment Chemicals
- Plastic Fabrication

Products for Printed Circuit Manufacture



Kolon Dry Film Resists

Kolon dry film resists for PCB manufacturing and chemical milling. PK1500 and PK1600 are available in 30, 40 and 50 micron thicknesses.

- Excellent adhesion and chemical resistance
- Rapid developing with minimal foam generation
- Strips rapidly producing small filterable particles
- Competitive pricing



PK1640 L/S 40/40μ

Copper Cleaners and Micro Etch

- Copperwet 1120 – Pre plate cleaner
- Copperwet 1130 – Combined degreaser and mild micro etch for prior to HAL
- Copperwet 1150 – Non foaming, non etching spray cleaner, no attack on Stainless Steel
- Copperwet 1170 – Micro etch prior to plating
- Copperwet 1174 – Micro Etch prior to silver
- Copperwet 1195 – Post graphite microetch
- Glibrite GB-4300R40 – Surface roughener for optimum adhesion of dry film and photoimageable resists

Copper topography for Glibrite

E/A	GB-4300	Parameter (μm)	Competitor	Parameter (μm)
0.3 μm		Ra=0.14		Ra=0.24
		Rz=1.2		Rz=2.2
		RSm=2.1		RSm=3.5
0.5 μm		Ra=0.16		Ra=0.29
		Rz=1.4		Rz=2.5
		RSm=1.2		RSm=2.5
1.0 μm		Ra=0.19		Ra=0.38
		Rz=1.5		Rz=3.2
		RSm=0.9		RSm=1.2

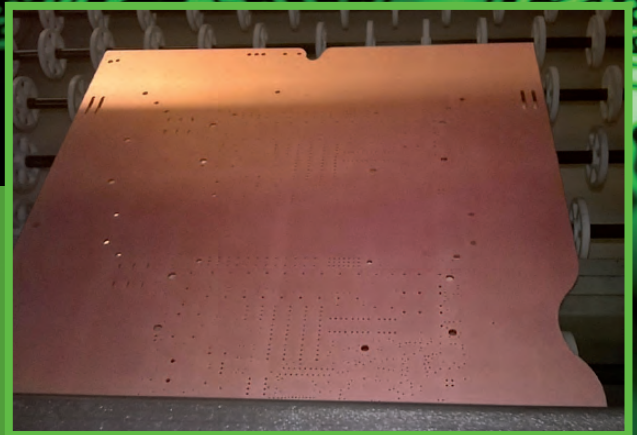


Direct Metallisation and Electroplating

ViaKing METALLISATION

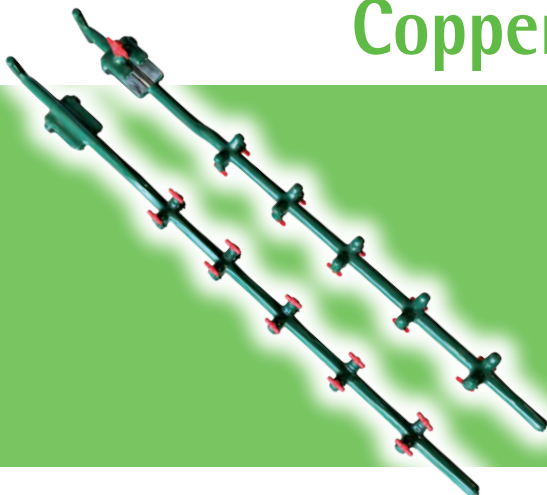
Unique new generation carbon / graphite process providing exceptional conductivity.

- DS280 Conditioner
- 202-E Conductivator
- Microetch 1195
- PAT790 Anti Tarnish



Copper and Tin Plating

- CU90H – Acid copper for complex circuits with blind or micro-vias
- CU400 – High speed, 1:1 surface to hole-wall copper distribution, bright, ductile copper
- SN800 – Reliable, easy to control Sulphuric Acid based Tin Plating Solution
- Plating Jigs – Plastic coated copper cored stainless steel jigs manufactured to customer dimensions. Full refurbishment service also available



Resist strippers, Developers

and Antifoams

- **Aquastrip 1310** - Low cost Potassium Hydroxide based stripper for high volume circuit production or chemical milling
- **Aquastrip 1320** - Highly effective on overplated boards
- **Aquastrip 1330, 1335 and 1340** - Organic strippers with no effect on Tin Plating Resist strips in filterable particles for volume production
- **Developer 1648** - Concentrated developer for use in spray equipment, suitable for all aqueous dry films and photoimagable inks
- **Antifoam 200NS** - Highly concentrated antifoam for water treatment and stripping solutions
- **Antifoam 700NS** - For developer and stripper. Low residue
- **Antifoam 800NS** - Latest generation for developer and stripper

Desmear and Multilayer Bonding

Desmear

Resin Swell 7100, Desmear 7110 plus Neutraliser 7135 to achieve perfect micro-roughness for three point connection.

Top Bond Oxide Replacement

Conditioner 7876, Pre-Dip 7877 and Promoter 7878 to enhance bond strength and eliminate delamination of multi-layer PCBs.

Tin Strippers

- **Tin Stripper 1532 and 1535** - Spray, Nitric Acid based products for volume production with minimal attack on copper
- **Tin Stripper 1542** - Immersion stripper with NO copper attack even when fully loaded

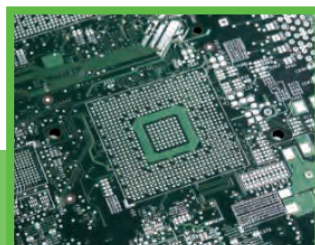


Solder analysis

HAL Fluxes and Solder

- **1295EM** - Suitable for Tin / Lead and Lead Free Solder
- **1298SD** - Latest generation flux producing bright, level deposits with no solder pick up
- **SN100SB** - Lead Free Solder producing bright, solderable deposits. Full customer analysis service is available using Spark Erosion equipment as well as dross collection

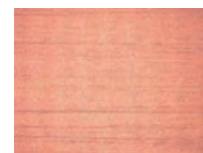
Solderable Finishes



IAG 377M Silver - Unique, alkaline immersion silver, producing bright, easily soldered tarnish resistant deposits. 6 month shelf life. **Preclean Copperwet 1120, Microetch 1174, Predip PX313, Silver 377M, Antitarnish ANT 39.**

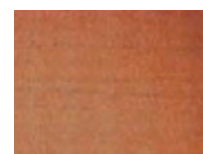
Copper oxidation thickness

After ageing



42Å

After ageing and reflow 5 times



173Å

Glicoat SMD F2 (2X)

Organic solderable coating for volume production. Produces a uniform, very thin coating by reacting with copper only.

Screen Printing Inks and Ancillary Products

BLT distribute the competitive range of Sun Chemical photoimagable and screen printable inks.

- Stencil preparation chemicals
- Direct and Indirect Stencil Films
- Squeegees
- Screen washes

SunChemical



Tapes and Filters

Tapes – 9180 Gold Plating Tape, Splashback Tape, Red Litho Tape and CM8R Hot Air Levelling Tape.

Polypropylene, wound filters for general use 10", 20" and 30" in 0.5 to 100 micron pore sizes.

Water Treatment Chemicals

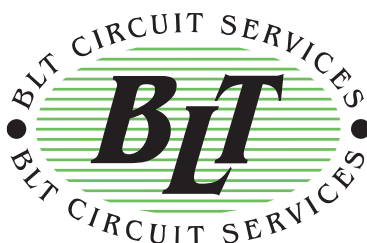
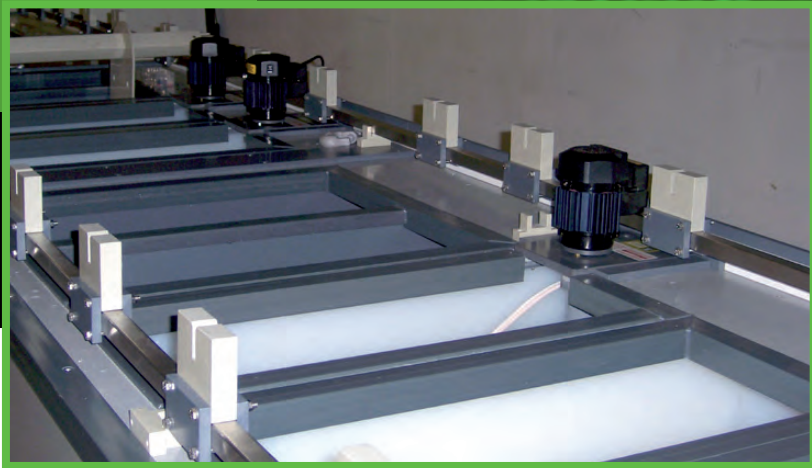
- ANF 30 Anionic Flocculant – for use prior to settlement
- M25 Cationic Flocculant – for use with MP15 metal precipitant
- MP15 – Highly effective complex breaking chemical to remove copper from waste streams

Plastic Fabrication

BLT manufacture complete, bespoke plating lines, cleaning lines, water treatment plants plus a range of Etch, Developer and pH controllers.

Settlement tank

Plating line



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